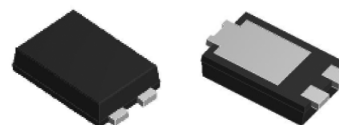


Features

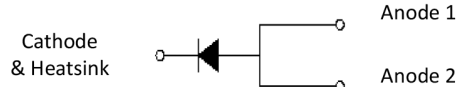
- Heatsink design
- Schottky barrier diodes
- Low forward voltage drop
- Low leakage current
- Solder dip 260 °C, 10 s
- Low profile - typical height of 1.1 mm
- Moisture sensitivity: level 1, per J-STD-020
- Halogen-free according to IEC 61249-2-21 definition
- High temperature soldering guaranteed: 260°C/10 seconds



RoHS
COMPLIANT



eSGC (TO-277)



Typical Applications

For low voltage high frequency inverters, DC/DC converters and polarity protection application.

Maximum Ratings (TA = 25 °C unless otherwise noted)

Parameter	Symbol	SGC1508S	SGC151BS	Unit
Maximum repetitive peak reverse voltage	VRRM	80	100	V
Maximum RMS voltage	VRMS	56	70	V
Maximum DC blocking voltage	VDC	80	100	V
Maximum average forward rectified current	IF(AV) ¹⁾	8.0		A
	IF(AV) ²⁾	15.0		
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	IFSM	250		A
Operating junction and storage temperature range	TJ, TSTG	-55 to +150		°C

Electrical Characteristics (TA = 25 °C unless otherwise noted)

Parameter	Test Conditions		Symbol	Typ.	Max.	Unit
Instantaneous forward voltage	I _F =2A	T _A =25°C	V _F	0.39	0.42	Volts
	I _F =5A			0.44	0.47	
	I _F =10A			0.51	-	
	I _F =15A			0.57	0.65	
	I _F =5A	TA=125°C		0.35	-	
	I _F =15A			0.52	0.6	
Reverse current	VR=100V	T _A =25°C	I _R	29	100	uA
		T _A =125°C		26	50	mA
Typical junction capacitance	4.0 V, 1 MHz		C _J	1.78		nF
Typical thermal resistance	junction to ambient		R _{θJA} ¹⁾	35		°C/W
	junction to lead		R _{θJL} ²⁾	3.5		°C/W

Notes, 1) Thermal resistance RθJA is junction to lead, mounted on P.C.B with 30*30mm copper pad area

2) Thermal resistance RθJM is junction to lead, mounted on aluminum substrate P.C.B

Ratings and Characteristics Curves

(TA = 25°C unless otherwise noted)

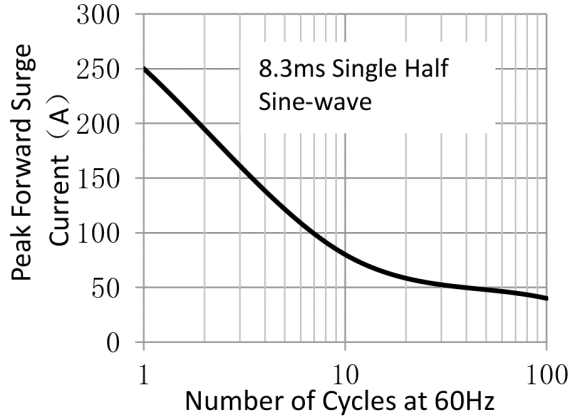


Figure 1. Maximum Non-Repetitive Peak Forward Surge Current

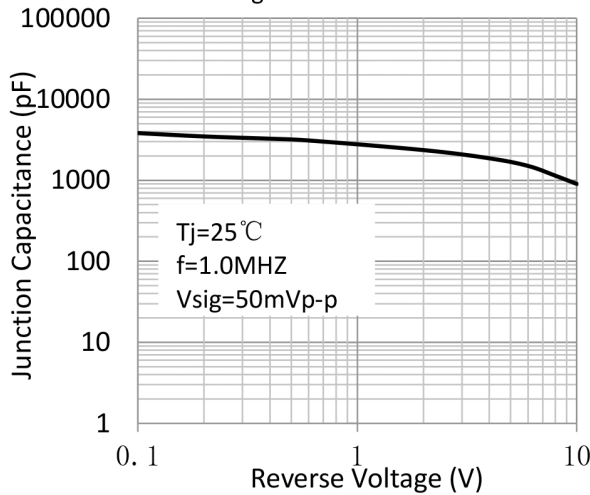


Figure 3. Typical Junction Capacitance

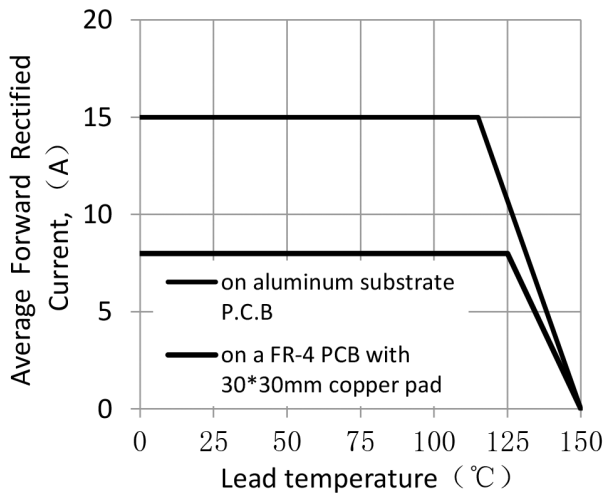


Figure 5. Forward Current Derating Curve

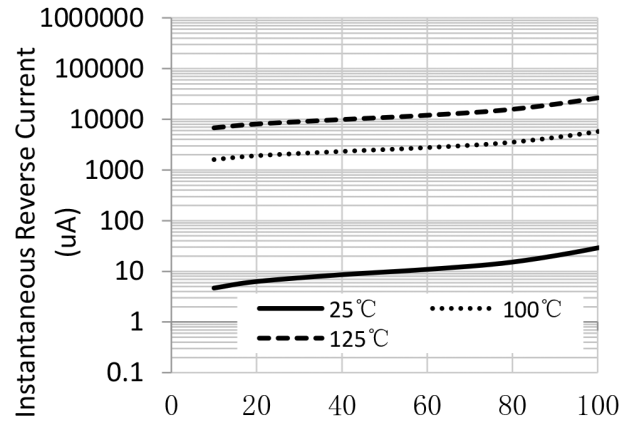


Figure 2. Typical Reverse Characteristics

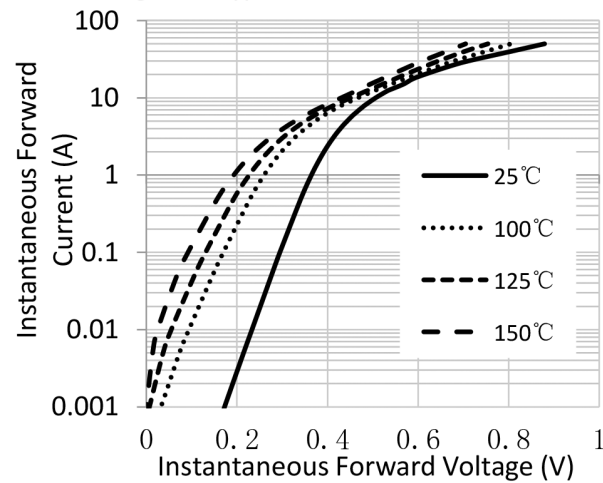
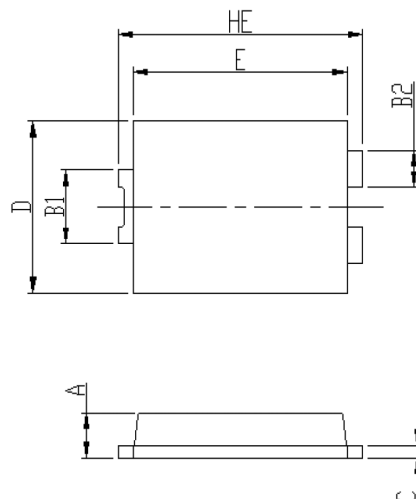
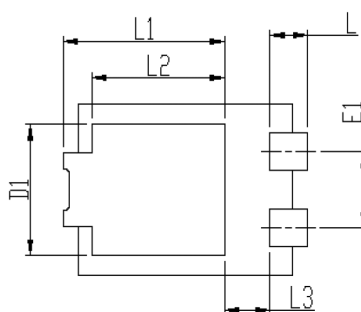


Figure 4. Typical Instantaneous Forward Characteristics

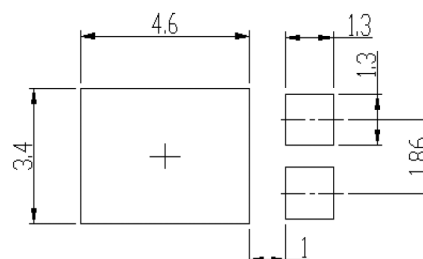
Package Outline Dimensions



DIM	Unit: mm		Unit: inch	
	MIN	MAX	MIN	MAX
HE	6.4	6.6	0.252	0.260
E	5.6	5.8	0.220	0.228
D	4.1	4.3	0.161	0.169
B1	1.7	1.9	0.067	0.075
B2	0.8	1	0.031	0.039
A	1.05	1.2	0.041	0.047
C	0.3	0.4	0.012	0.016
L	0.85	1.1	0.033	0.043
L1	4.2	4.4	0.165	0.173
L2	3.52 Typ.		0.139 Typ.	
L3	1.1	1.4	0.043	0.055
D1	3	3.3	0.118	0.130
E1	1.86 Typ.		0.073 Typ.	



Soldering footprint



Packing Information

Packing quantities:

5000 pcs/Reel, 12mm Tape, 13" Reel

Tape & Reel Specification

